



## Tecbond 240

Version: Tecbond 240-TDS  
Date of last issue: 15/07/2025  
Date of first issue: 7/7/2015

### General description

Tecbond 240 is a high-performance adhesive that is available in clear and coloured versions. It is medium viscosity and has a medium open time. It provides excellent bonds on wood, paper, card, light gauge metals and many plastics. Being medium viscosity, it gives improved adhesive applicator output, less stringing and tighter bond lines.

### Substrates\*

- Paper
- Cardboard
- Wood
- Light gauge metals
- Plastic (not PP or PE)

### Technical characteristics

**Adhesive type:** Synthetic polymer based hotmelt

**Colour:** Clear and coloured and glitter versions available

**Molten tack:** Medium

**Bulk Format:** None

	7mm / ¼"	12mm / ½"	15mm / ⅝"	43mm / 1¾"
<b>Carton QTY</b>	14kg / 31lb	5kg / 11lb	5kg / 11lb	10kg / 22lb
<b>Suggested application temperature</b>	195°C / 380°F	195°C / 380°F	195°C / 380°F	195°C / 380°F
<b>Brookfield viscosity @180°C (POW-12-VISC) spindle 27</b>	7500cps	7500cps	7500cps	7500cps
<b>Ring &amp; ball softening point (ASTM E28)</b>	87°C / 189°F	87°C / 189°F	87°C / 189°F	87°C / 189°F
<b>Heat resistance (BS5350 Part H3)</b>	80°C / 176°F	80°C / 176°F	80°C / 176°F	80°C / 176°F
<b>Open time</b>	30 secs	30 secs	30 secs	30 secs
<b>Brittle point</b>	-10°C / 14°F	-10°C / 14°F	-10°C / 14°F	-10°C / 14°F



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# Technical Data Sheet

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## Storage

Store in a clean dry place at temperatures between 5°C / 41°F and 30°C / 86°F with boxes closed. Do not expose to direct sunlight or localised heat sources such as radiators or hot pipes.

## Shelf life

Manufacturer guarantees 5-year shelf life after date of manufacture in accordance with suitable storage conditions as mentioned above.

## Methods of application

Bead Adhesive Applicator.

## Removal of adhesive

Assembled components can be separated by heating assembly to a temperature slightly above the heat resistance figure.

**EVA & Polypropylene:** Residues of EVA and polypropylene based hotmelts can be removed from components with white spirit.

**Polyamide:** Residues of polyamide based hotmelt can be removed from components with acetone

## Disclaimer

The information contained on this data sheet is for guidance only. It is the result of careful laboratory evaluations by trained and qualified staff using British Standard or similar test methods. However, no warranty is expressed or implied regarding the accuracy of the data or the suitability of the adhesive for any specific purpose. In every case, we strongly recommend that the user shall make their own test to determine to their own satisfaction the suitability of the adhesive for their particular purpose. Neither the seller nor manufacturer shall be liable for any injury, loss, damage, direct or consequential arising out of the use or inability to use the product. Further information is always available to help solve your adhesive problems. Should you require any further information on our adhesives please contact your nearest distributor.

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*F.D.A. approved. All the constituent parts of this adhesive have been approved by the American F.D.A. under C.F.R. 21.175.105 (adhesives) (subject to limitations).*